Plaskon S-7PG

Epoxy; Epoxide

Cookson Electronics - Semiconductor Products

Message:

This material is a low stress, low viscosity epoxy encapsulant designed for packaging stress-sensitive semiconductor devices. It is specifically formulated to provide a lower viscosity for those low stress applications where wire sweep may be a concern. It offers end users superior value-in-use due to a balanced mix of properties.

General Information			
Features	Semi-conductive Low viscosity Laser marking Good formability Excellent appearance		
Forms	Liquid		
Processing Method	Resin transfer molding		
Physical	**Nominal Value**	**Unit**	**Test Method**
Specific Gravity	1.84	g/cm³	ASTM D792
Molding Shrinkage - Flow	0.47	%	ASTM D955
Mechanical	**Nominal Value**	**Unit**	**Test Method**
Tensile Strength	0.00637	MPa	ASTM D638
Flexural Modulus	1.31	MPa	ASTM D790
Flexural Strength (21°C)	0.0107	MPa	ASTM D790
Thermal	**Nominal Value**	**Unit**	**Test Method**
Glass Transition Temperature	170	°C	ASTM E1356
CLTE - Flow	1.8E-5	cm/cm/°C	ASTM D696
Thermal Conductivity	16	W/m/K	ASTM C177
Electrical	**Nominal Value**	**Unit**	**Test Method**
Volume Resistivity	5.5E+15	ohms·cm	ASTM D257
Dielectric Strength	16	kV/mm	ASTM D149
Dielectric Constant (1 kHz)	3.60		ASTM D150
Dissipation Factor (1 kHz)	4.0E-3		ASTM D150
Arc Resistance	180	sec	ASTM D495
Flammability	**Nominal Value**	**Unit**	**Test Method**
Flame Rating (3.18 mm)	V-0		UL 94
Oxygen Index	32	%	ASTM D2863
Additional Information			

Recommended Storage Temperature: 5°CLife @ 5°C, defined as not more than 40% loss of spiral flow based on original values.: 24 monthsLife @ 21°C, defined as not more than 40% loss of spiral flow based on original values.: 5 daysLife @ 35°C, defined as not more than 40% loss of spiral flow based on original values.: 2 daysSpiral Flow, 175°C, 1000 psi: 60 to 90 cmAutomatic Orifice Viscosity, 175°C, 1000 psi, 1 mm die length, 1/2 mm diameter: 9 Pascal secRam Follower Gel Time, 177°C: 10 to 18 secAsh Content: 73.7 %Hydrolyzable Halides: <1 ppmCull Hot Hardness, Shore D, 90 sec, 175°C: 70Arc Resistance, 110v AC180 secAll test specimens are transfer molded and post cured for 4 hours at 175°C
Linear Thermal Expansion, Alpha 1: 18 cm^-6/cm/°C
Linear Thermal Expansion, Alpha 2: 65 cm^-6/cm/°C

Injection instructions

Resin Transfer Molding:
Preheat Temperature: 85 to 95°C
Molding Temperature: 170 to 185°C
Molding Pressure: 900 to 1200 psi
Cure Time, 177°C: 1 to 2min
Post Mold Cure Time, 175°C: 4 to 12 hr

Recommended distributors for this material

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